

DUAL N-CHANNEL 450V - 4.1Ω - 0.4A SO-8 SuperMESH™ POWER MOSFET

| TYPE | V_{DSS} | R _{DS(on)} | ID |
|-----------|------------------|---------------------|-------|
| STS1DNC45 | 450 V | < 4.5 Ω | 0.4 A |

- TYPICAL $R_{DS}(on) = 4.1\Omega$
- STANDARD OUTLINE FOR EASY AUTOMATED SURFACE MOUNT ASSEMBLY
- GATE CHARGE MINIMIZED

DESCRIPTION

The SuperMESH[™] series is obtained through an extreme optimization of ST's well established stripbased PowerMESH[™] layout. In addition to pushing on-resistance significantly down, special care is taken to ensure a very good dv/dt capability for the most demanding applications. Such series complements ST full range of high voltage MOSFETs including revolutionary MDmesh[™] products.

APPLICATIONS

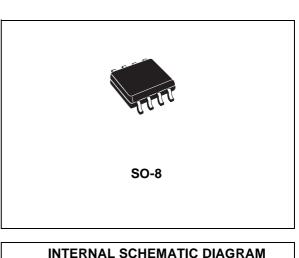
- SWITCH MODE LOW POWER SUPPLIES (SMPS)
- DC-DC CONVERTERS
- LOW POWER, LOW COST CFL (COMPACT FLUORESCENT LAMPS)
- LOW POWER BATTERY CHARGERS

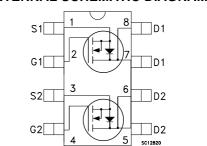
ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|-------------------------------|--|--------------|--------|
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 450 | V |
| V _{DGR} | Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$) | 450 | V |
| V_{GS} | Gate- source Voltage | ± 30 | V |
| Ι _D | Drain Current (continuous) at $T_C = 25^{\circ}C$ Drain Current (continuous) at $T_C = 100^{\circ}C$ | 0.40 0.25 | A A |
| $I_{DM}\left(\bullet ight)$ | Drain Current (pulsed) | 1.6 | Α |
| P _{TOT} | Total Dissipation at $T_C = 25^{\circ}C$ Dual Operation Total Dissipation at $T_C = 25^{\circ}C$ Single Operation | 1.6 2 | W W |
| dv/dt(1) | Peak Diode Recovery voltage slope | 3 | V/ns |

(•) Pulse width limited by safe operating area

(1) $I_{SD} \le 0.4$ A, di/dt ≤ 100 A/µs, $V_{DD} \le V_{(BR)DSS}$, $T_j \le T_{JMAX}$.





THERMAL DATA

| Rthj-amb(#) | Thermal Resistance Junction-ambient Max Single Operation Thermal Resistance Junction-ambient Max Dual Operation | 62.5 78 | °C/W °C/W |
|------------------|--|------------|--------------|
| Tj | Max. Operating Junction Temperature | 150 | °C |
| T _{stg} | Storage Temperature | –65 to 150 | °C |

(#) When Mounted on FR4 board (Steady State)

AVALANCHE CHARACTERISTICS

| Symbol | Parameter | Max Value | Unit |
|-----------------|---|-----------|------|
| I _{AR} | Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max) | 0.4 | A |
| E _{AS} | Single Pulse Avalanche Energy (starting $T_j = 25 \text{ °C}, I_D = I_{AR}, V_{DD} = 50 \text{ V}$) | 30 | mJ |

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|----------------------|--|---|------|------|------|------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | $I_{D} = 250 \ \mu A, \ V_{GS} = 0$ | 450 | | | V |
| I _{DSS} | Zero Gate Voltage | V _{DS} = Max Rating | | | 1 | μA |
| | Drain Current (V _{GS} = 0) | V_{DS} = Max Rating, T_{C} = 125 °C | | | 50 | μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | $V_{GS} = \pm 30V$ | | | ±100 | nA |

ON (1)

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------|--------------------------------------|--|------|------|------|------|
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 2.3 | 3 | 3.7 | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 10 V, I _D = 0.5 A | | 4.1 | 4.5 | Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---------------------|---------------------------------|--|------|------|------|------|
| g _{fs} (1) | Forward Transconductance | $V_{DS} = 25 V, I_D = 0.5 A$ | | 1.1 | | S |
| C _{iss} | Input Capacitance | $V_{DS} = 25 \text{ V}, \text{ f} = 1 \text{ MHz}, V_{GS} = 0$ | | 160 | | pF |
| Coss | Output Capacitance | | | 27.5 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 4.7 | | pF |

ELECTRICAL CHARACTERISTICS (CONTINUED)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--|--|---|------|-----------------|------|----------------|
| t _{d(on)} | Turn-on Delay Time | V _{DD} = 225 V, I _D = 0.5 A | | 6.7 | | ns |
| t _r | Rise Time | $R_G = 4.7\Omega V_{GS} = 10 V$ (see test circuit, Figure 3) | | 4 | | ns |
| Q _g Q _{gs} Q _{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 360 \text{ V}, I_D = 1.5 \text{ A},$ $V_{GS} = 10 \text{ V}$ | | 7 1.3 3.2 | 10 | nC nC nC |

SWITCHING OFF

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---|---|-----------------|------|-----------------|------|----------------|
| t _{r(off)} t _f t _c | Off-voltage Rise Time Fall Time Cross-over Time | | | 8.5 12 18 | | ns ns ns |

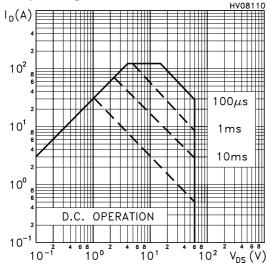
SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|--|--|--|------|-------------------|------|---------------|
| I _{SD} | Source-drain Current | | | | 0.4 | А |
| I _{SDM} (2) | Source-drain Current (pulsed) | | | | 1.6 | А |
| V _{SD} (1) | Forward On Voltage | $I_{SD} = 0.4 \text{ A}, V_{GS} = 0$ | | | 1.6 | V |
| t _{rr} Q _{rr} I _{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $\begin{split} I_{SD} &= 0.4 \text{ A, di/dt} = 100 \text{A/} \mu \text{s,} \\ V_{DD} &= 100 \text{ V, } T_{j} = 150^{\circ}\text{C} \\ (\text{see test circuit, Figure 5}) \end{split}$ | | 225 530 4.7 | | ns nC A |

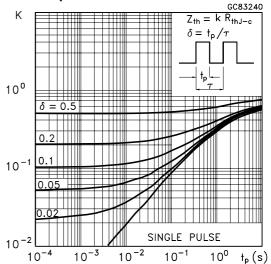
Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

2. Pulse width limited by safe operating area.

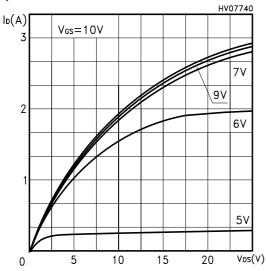
Safe Operating Area



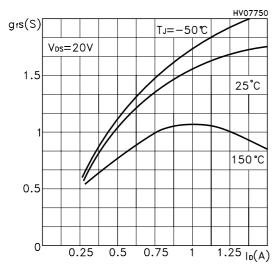
Thermal Impedance



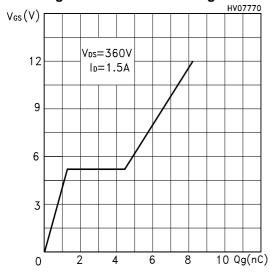
Output Characteristics

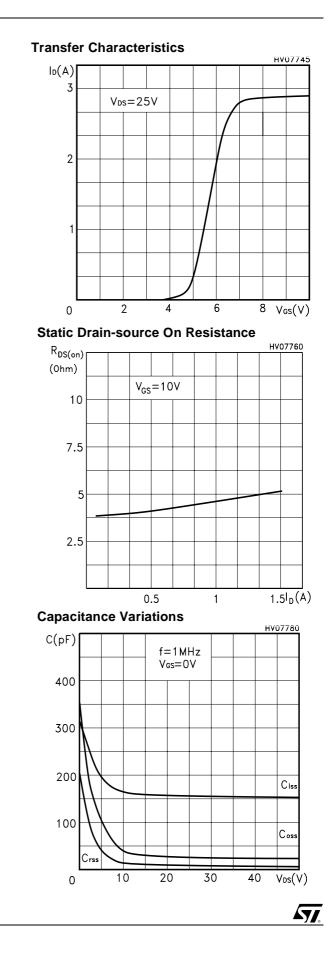


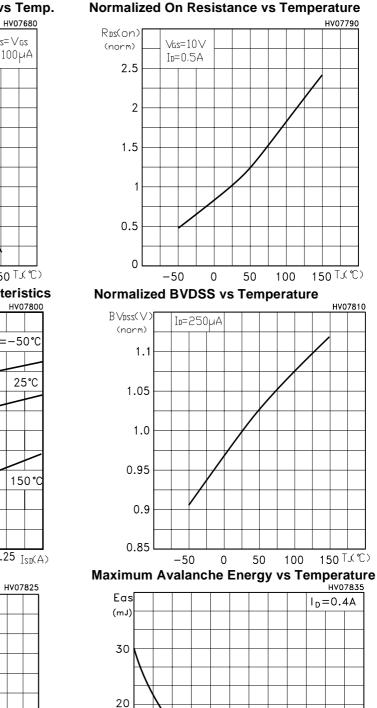
Transconductance



Gate Charge vs Gate-source Voltage







10

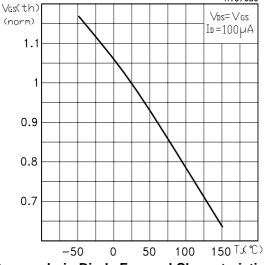
50

75

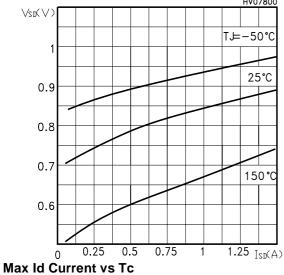
100

125

Normalized Gate Threshold Voltage vs Temp.



Source-drain Diode Forward Characteristics



HV07825 $I_{\alpha}(A)$ 0.5 0.4 0.3 0.2 0.1 0.2 0.1 0.2 0.1 0.2 0.1 0.2 0.1 0.5 0.5 0.1 0.5 0.2 0.1 0.2 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5 0.5 0.1 0.5

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150 ℃ ℃

Fig. 1: Unclamped Inductive Load Test Circuit

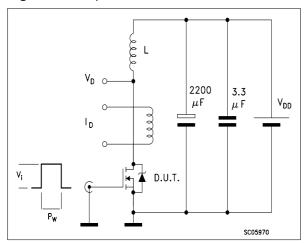


Fig. 3: Switching Times Test Circuit For Resistive Load

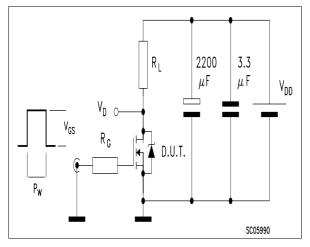


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times

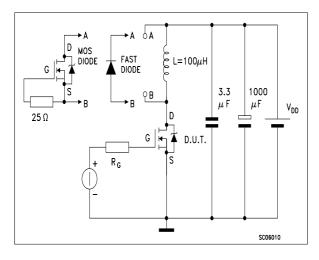


Fig. 2: Unclamped Inductive Waveform

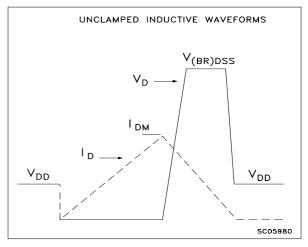
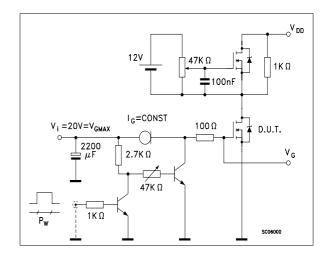
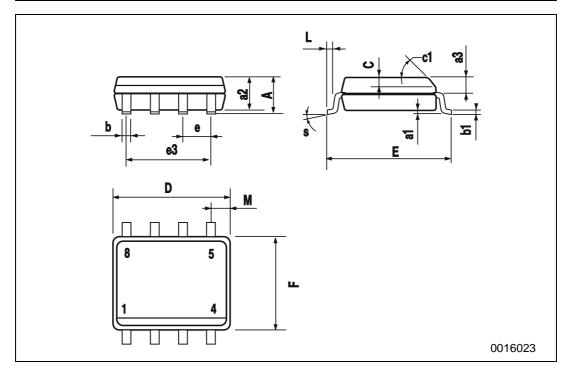


Fig. 4: Gate Charge test Circuit



| mm | | | inch | | | |
|------|--|---------------------------------|---|---|---|--|
| MIN. | TYP. | MAX. | MIN. | TYP. | MAX. | |
| | | 1.75 | | | 0.068 | |
| 0.1 | | 0.25 | 0.003 | | 0.009 | |
| | | 1.65 | | | 0.064 | |
| 0.65 | | 0.85 | 0.025 | | 0.033 | |
| 0.35 | | 0.48 | 0.013 | | 0.018 | |
| 0.19 | | 0.25 | 0.007 | | 0.010 | |
| 0.25 | | 0.5 | 0.010 | | 0.019 | |
| | | 45 | (typ.) | | | |
| 4.8 | | 5.0 | 0.188 | | 0.196 | |
| 5.8 | | 6.2 | 0.228 | | 0.244 | |
| | 1.27 | | | 0.050 | | |
| | 3.81 | | | 0.150 | | |
| 3.8 | | 4.0 | 0.14 | | 0.157 | |
| 0.4 | | 1.27 | 0.015 | | 0.050 | |
| | | 0.6 | | | 0.023 | |
| | 0.1 0.65 0.35 0.19 0.25 4.8 5.8 3.8 | MIN. TYP. 0.1 | MIN. TYP. MAX. 1.75 1.75 0.1 0.25 1.65 0.85 0.65 0.85 0.35 0.48 0.19 0.25 0.25 0.5 4.8 5.0 5.8 6.2 1.27 3.81 3.8 4.0 0.4 1.27 | MIN. TYP. MAX. MIN. 1.75 1.75 1.75 0.1 0.25 0.003 1.65 1.65 0.025 0.65 0.85 0.025 0.35 0.48 0.013 0.19 0.25 0.007 0.25 0.5 0.010 45 (typ.) 4.8 5.0 0.188 5.8 6.2 0.228 1.27 3.81 1.27 3.8 4.0 0.14 0.4 1.27 0.015 | MIN. TYP. MAX. MIN. TYP. 1.75 1. | |

SO-8 MECHANICAL DATA



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